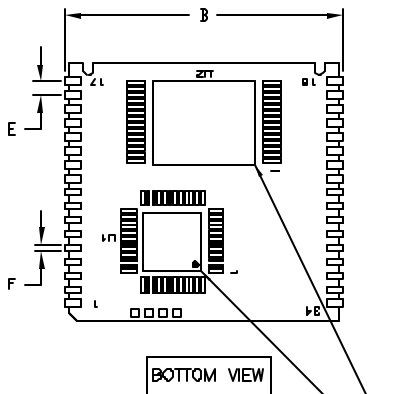
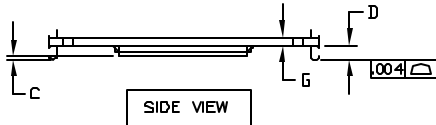
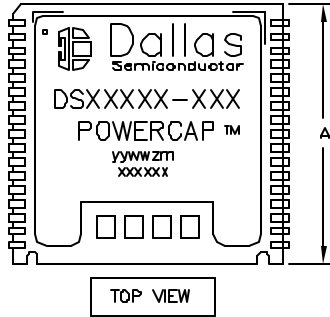


PowerCap™ Module Base





COMPONENTS AND PLACEMENT MAY VARY BY DEVICE TYPE.

REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
A	New drawing	11/04	JW
A1	ECN 47775 DIMENSION UNDER PCAP COMPONENTS		

PKG DIM	INCHES		
	MIN	NOM	MAX
A	0.920	0.925	0.930
B	0.980	0.985	0.995
C	0.002	—	—
D	0.050	0.055	0.060
E	0.047	0.050	0.053
F	0.015	0.020	0.025
G	0.024	0.027	0.032

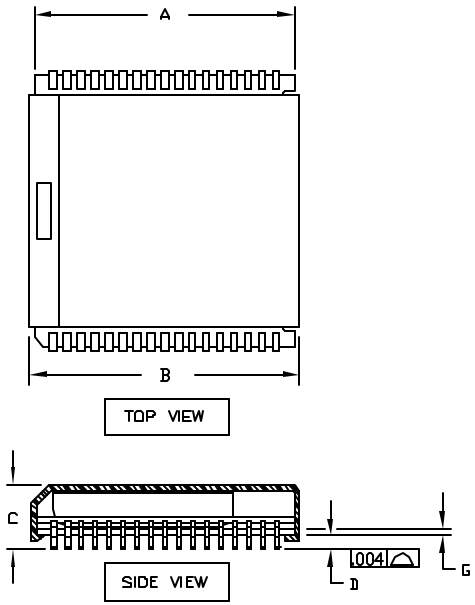
Notes:

1. Dallas Semiconductor recommends that PowerCap module bases experience one pass through solder reflow, oriented with the label side up ("live bug").
2. Hand soldering and touch-up: Do not touch or apply the soldering iron to leads more than 3 seconds. To solder, apply flux to the pad, heat the lead frame pad, and apply solder.
3. To remove the part, apply flux, heat the lead frame pad until the solder melts, then use solder wick to remove the solder.

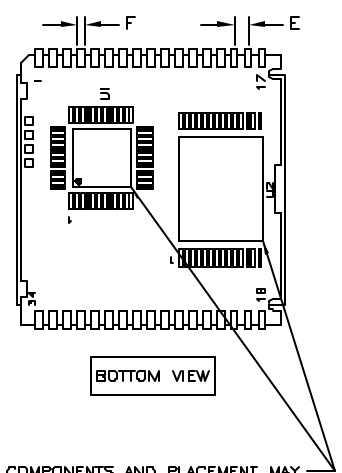
SIGNATURE	DATE	 			
DOC. CONTROL:					
ENGR. MGR:					
MFG. ENGR:					
CHECKED BY:					
DRAWN BY: M.ZUCCO	11/04	SIZE A	FSCN NO	DWG NO. 56-G0003-001	REV A1
DIP_Module(C)SL.DRW		SCALE N/A	SHEET 1 OF 3		

PowerCap™ .990
34 Pin PowerCap™ Module

PowerCap™ Base with DS9034PCX Attached



PKG	INCHES		
DIM	MIN	NOM	MAX
A	0.920	0.925	0.930
B	0.950	0.960	0.970
C	0.240	0.255	0.270
D	0.050	0.055	0.060
E	0.047	0.050	0.053
F	0.015	0.020	0.025
G	0.024	0.027	0.032



- Notes:
1. The DS9034PCX cap contains a lithium battery. Do not exceed 80°C.
 2. Remove the cap before touching up the base.
 3. If the base is washed, remove the cap before washing.
 4. If the base is washed, make sure it is dry before attaching the cap.

Recommended PowerCap™ Module Land Pattern

PKG DIM	INCHES		
	MIN	NOM	MAX
A	—	1.050	—
B	—	0.826	—
C	—	0.050	—
D	—	0.030	—
E	—	0.112	—

